

Electronic Patent Application Fee Transmittal

Application Number:	10791191			
Filing Date:	02-Mar-2004			
Title of Invention:	METHOD OF IMPROVING COPPER INTERCONNECTS OF SEMICONDUCTOR DEVICES FOR BONDING			
First Named Inventor/Applicant Name:	Salman Akram			
Filer:	James R. Duzan/Deidra Pfeil			
Attorney Docket Number:	3854.3US (98-0854.03/US)			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1440	1440
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
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Total in USD (\$)				1740